CRXSPS75M120G2Q

SiC MOSFET 1200V, 75mΩ, 32A

Features

- CRM G2 SIC MOSFET Technology
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Avalanche Ruggedness
- Fast Reverse Recovery
- AEC-Q101 Qualified

Product Summary

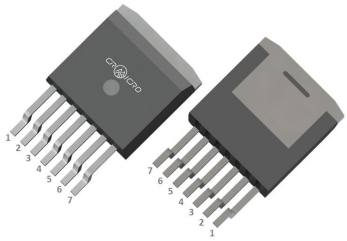
VDS	1200V
$R_{DS(on)_typ}$	75mΩ
I_D	32A

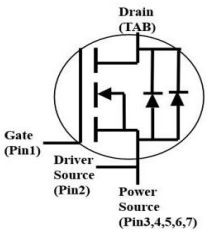
Applications

- Solar Inverters
- High Voltage DC/DC Converters
- On Board Charger(OBC)
- EV Charger

100% Avalanche Tested

RoHS HF





Package Marking and Ordering Information

Part #	Marking	Package	Packing	Qty
CRXSPS75M120G2Q	XS75M120G2Q	TO-263-7	Reel	800pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	1200	V
Continuous drain current V_{GS}=15V，T_C = 25°C V_{GS}=15V，T_C = 100°C	I_D	 32 23	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D(pulse)}$	80	A
Avalanche energy, single pulse (L=10mH, Rg=25Ω)	E_{AS}	360	mJ
Gate-Source voltage (dynamic)	V_{GSmax}	-10/+22	V
Gate-Source voltage (static)	V_{GSop}	-5/+18	V
Power dissipation (T_C=25°C,T_J=175°C)	P_D	136	W
Operating Junction and Storage Temperature	T_j,T_{stg}	-55...175	°C

a1: When using MOSFET Body Diode V_{GSmax} = -5V/+22V

a2: MOSFET can also safely operate at 0/+18 V

Thermal Resistance

Parameter	Symbol	Value	Unit
MOSFET Thermal resistance, junction – case. Max	R_{thJC}	1.1	°C/W
SBD Thermal resistance, junction – case. Max	R_{thJC}	1.4	
Thermal resistance, junction – ambient. Max	R_{thJA}	40	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	$V_{(BR)DSS}$	1200	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{GS(th)}$	1.8	-	3.6	V	V_{DS}=V_{GS},I_D=5mA
Zero gate voltage drain current	I_{DSS}	-	3	100	μA	V_{DS}=1200V,V_{GS}=0V T_j=25°C
		-	20	-		T_j=175°C
Gate-source leakage current	I_{GSS}	-	-	±100	nA	V_{GS}=-10/+22V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	75	90	mΩ	V_{GS}=15V, I_D=20A, T_j=25°C
		-	131	-		T_j=175°C
Drain-source on-state resistance	$R_{DS(on)}$	-	65	82	mΩ	V_{GS}=18V, I_D=20A, T_j=25°C
		-	127	-		T_j=175°C
Transconductance	g_{fs}	-	18	-	S	V_{DS}=20V,I_{DS}=20A
Dynamic Characteristic						
Internal Gate resistance	$R_{G(int)}$	-	1.8	-	Ω	f=1MHz
Input Capacitance	C_{iss}	-	1406	-	pF	V_{GS}=0V, V_{DS}=1000V, f=1MHz
Output Capacitance	C_{oss}	-	59	-		
Reverse Transfer Capacitance	C_{rss}	-	6.4	-		
Coss Stored Energy	E_{oss}	-	33	-	uJ	
Gate Total Charge	Q_g	-	69.5	-	nC	VGS=-5/18V VDS=800V ID=20A
Gate-Source charge	Q_{gs}	-	13	-		
Gate-Drain charge	Q_{gd}	-	19	-		
Turn-on delay time	$t_{d(on)}$	-	6.4	-	ns	VDD=800V,ID=20A VGS=-5V/15V, RG=2.5Ω，L=200uH
Rise time	t_r	-	10	-		
Turn-off delay time	$t_{d(off)}$	-	14.7	-		
Fall time	t_f	-	8.6	-		
Turn-On Switching Energy	$E_{(on)}$	-	44.8	-	uJ	
Turn Off Switching Energy	$E_{(off)}$	-	57.2	-		

Reverse Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Diode Forward Voltage	V_{SD}	-	1.9	-	V	V_{GS}=0V,I_F=20A
		-	3.5	-	V	V_{GS}=0V,I_F=20A, T_j=175℃
Continuous Diode Forward Current	I_S	-	-	32	A	V_{GS}=0V
Body Diode Reverse Recovery Time	t_{rr}	-	22	-	ns	di/dt=1000A/us IF=20A Vdd=800V Tj=25℃
Body Diode Reverse Recovery Charge	Q_{rr}	-	97.6	-	nC	
Body Diode Peak Reverse Recovery Current	I_{rrm}	-	7.1	-	A	

Typical Performance Characteristics

Fig 1. Output Characteristics (Tj=-55℃)

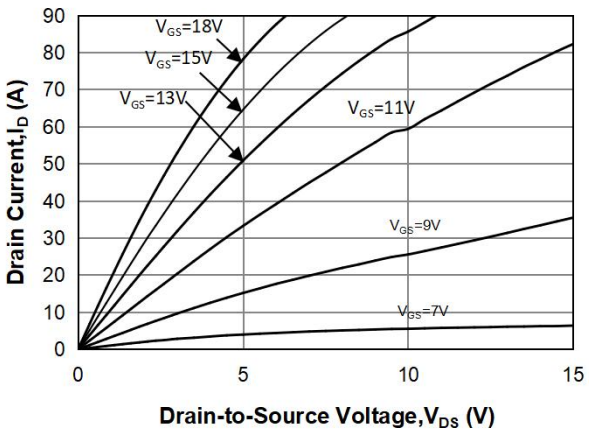


Fig 2. Output Characteristics (Tj=25℃)

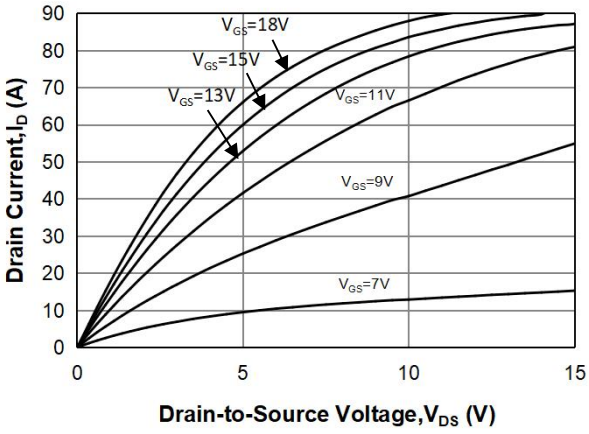


Fig 3. Output Characteristics (Tj=175℃)

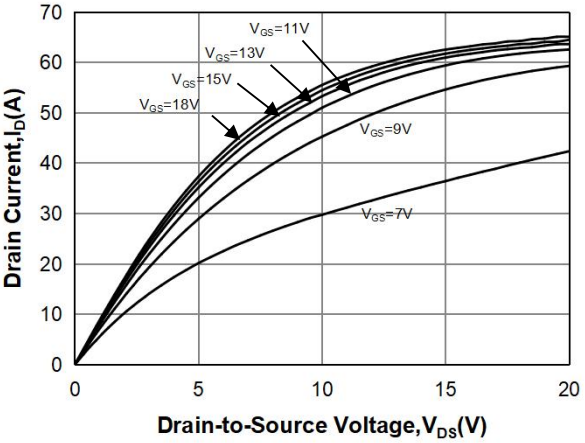


Fig 4: Rds(on) vs. Temperature

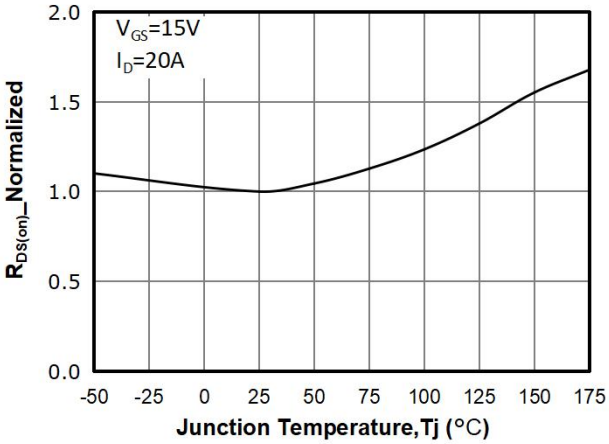


Fig 5: On-Resistance vs. Drain Current For Various Temperatures

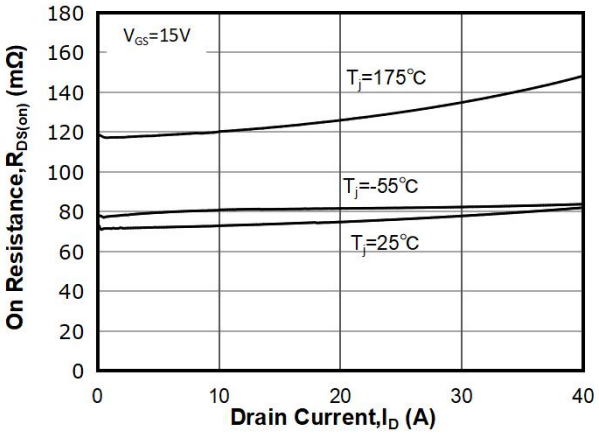


Fig 6: Rds(on) vs. Temperature For Various Gate Voltage

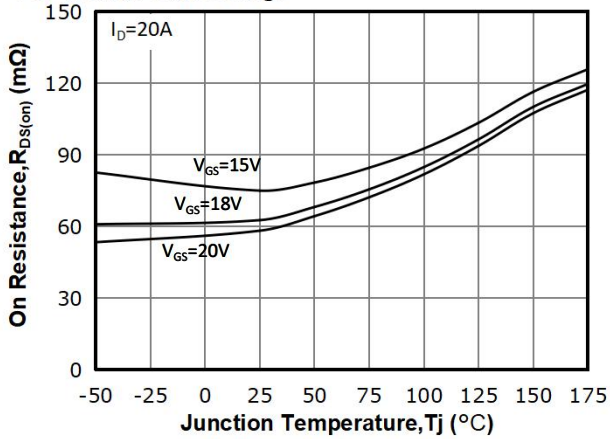


Fig 7: Transfer Characteristics

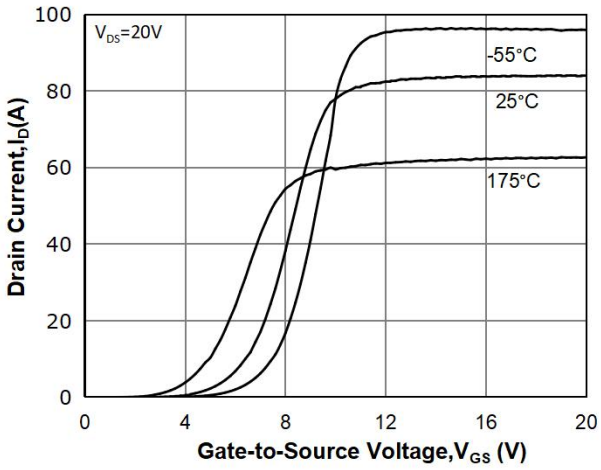


Fig 8: Body Diode Characteristic at 25℃

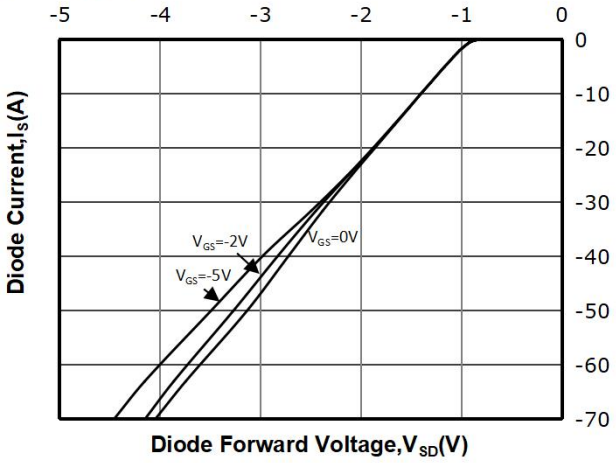


Fig 9: Body Diode Characteristic at 150℃

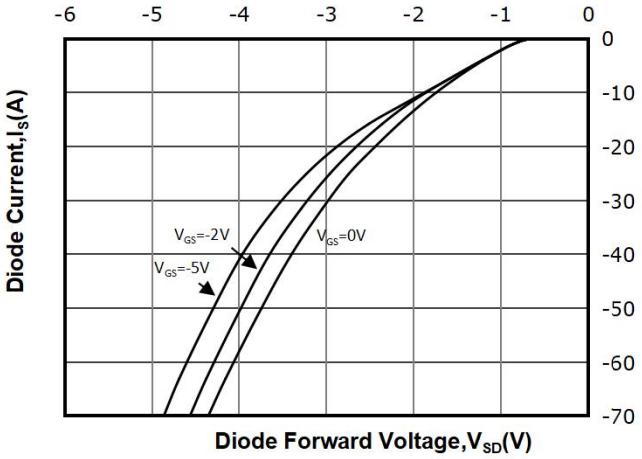


Fig 10: Body Diode Characteristic at 175℃

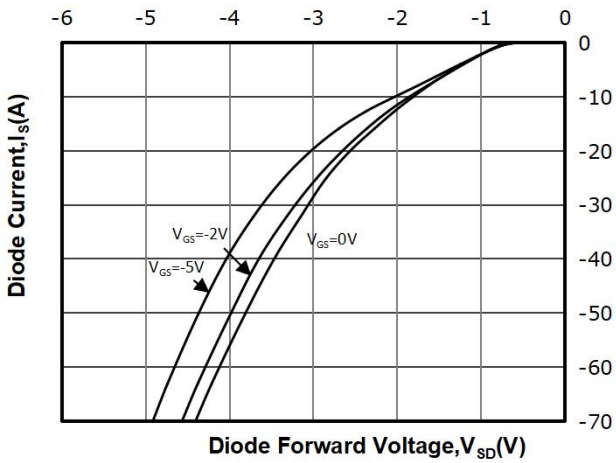


Fig 11: VGS(th) Vs Tj Characteristics

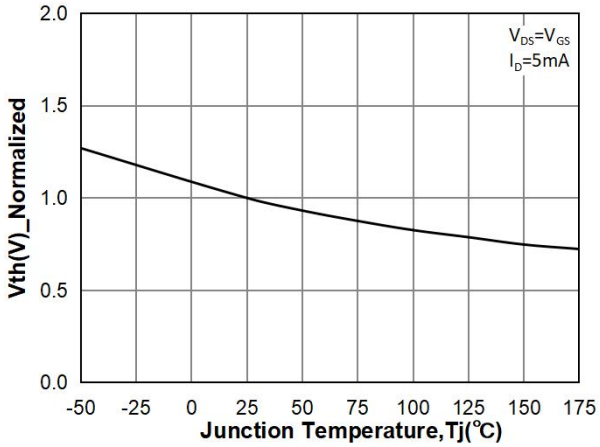


Fig 12: Gtate Charge Characteristics

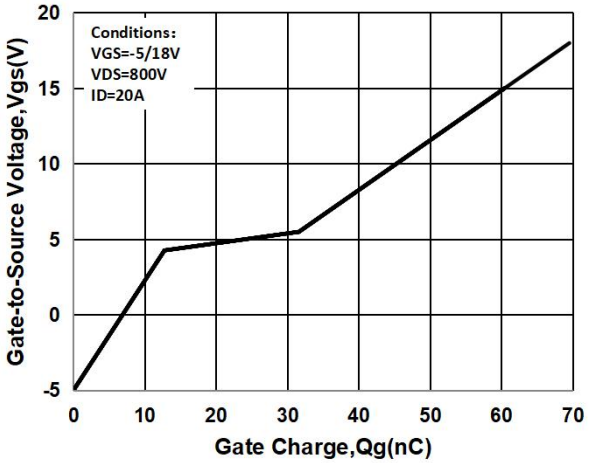


Fig 13: 3rd Quadrant Characteristic at 25℃

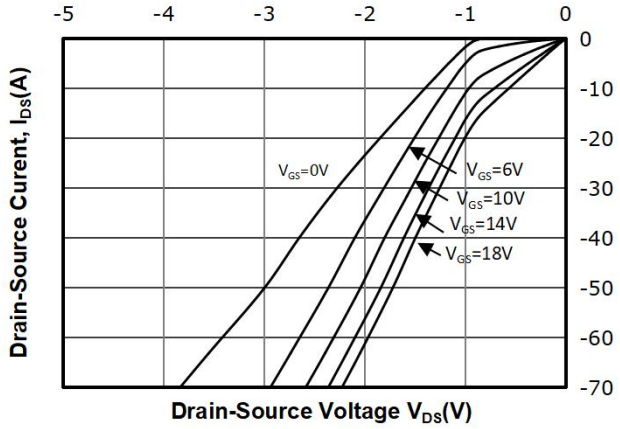


Fig 14: 3rd Quadrant Characteristic at 150℃

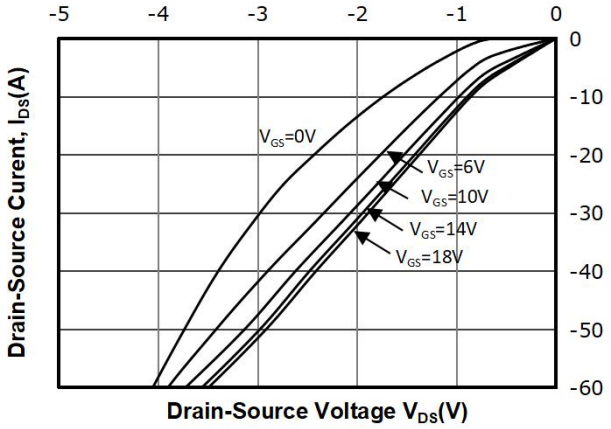


Fig 15: 3rd Quadrant Characteristic at 175℃

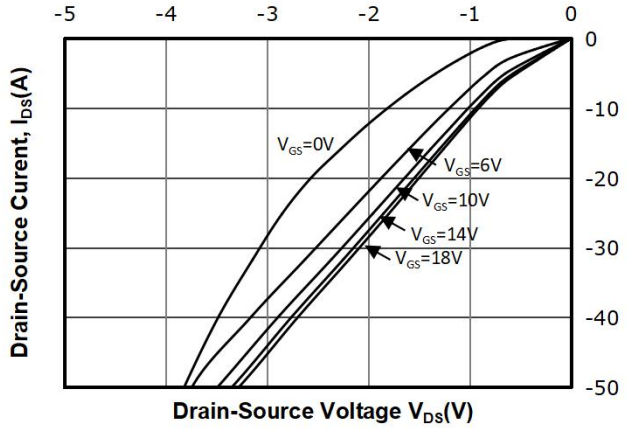


Fig 16: Capacitance Characteristics

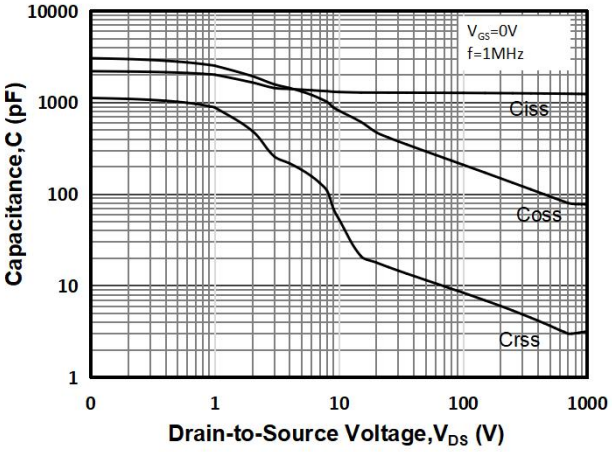


Fig 17:Output Capacitor Stored Energy

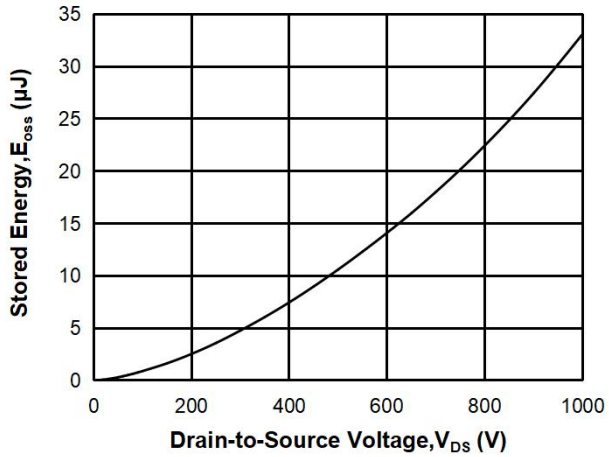


Fig 18: Forward Characteristic of Diode

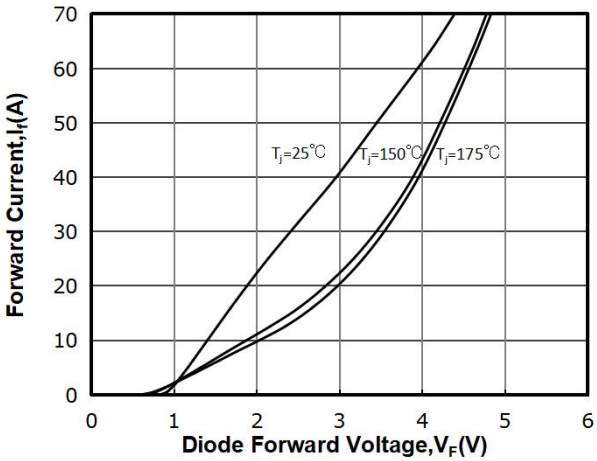


Fig 19: Continuous Drain Current vs. Case Temperature

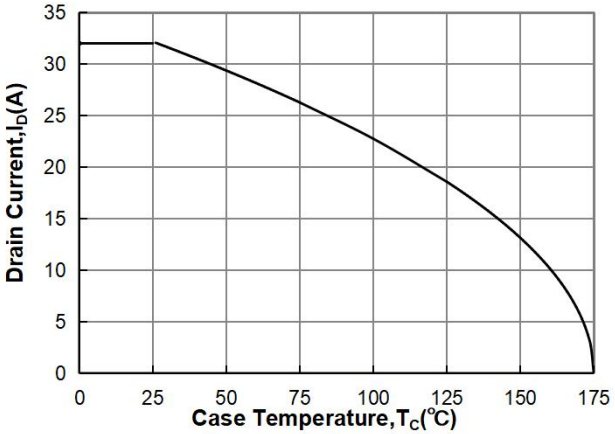


Fig 20: Maximum Power Dissipation vs. Case Temperature

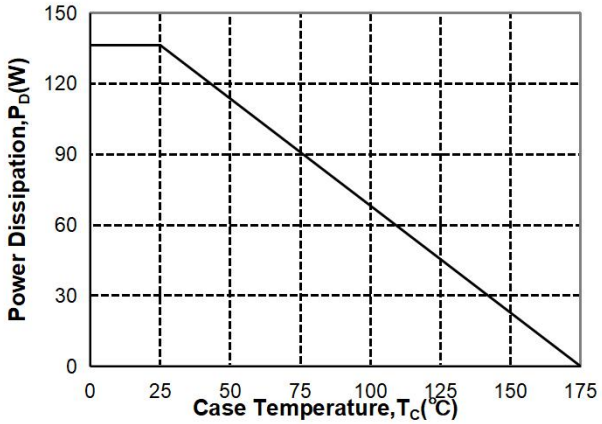


Fig.21：Peak forward current vs.Case temperature

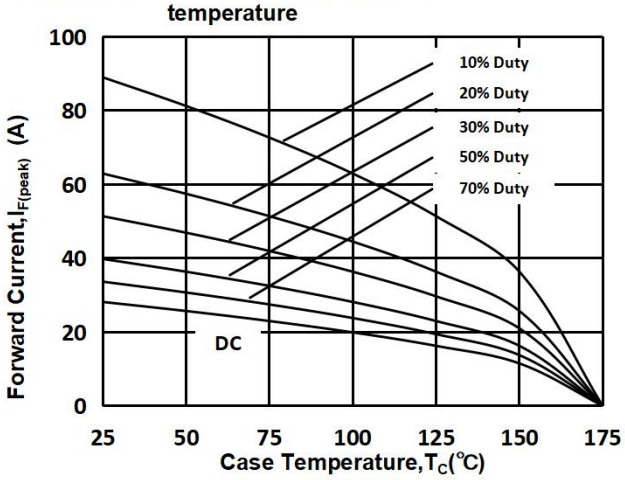


Fig 22: Safe Operating Area

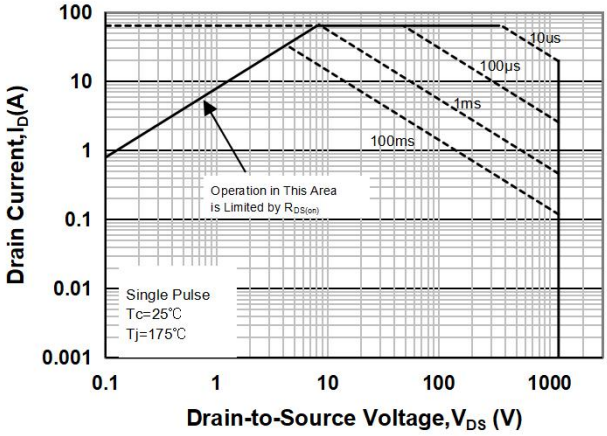


Fig 23: Max. Transient Thermal Impedance

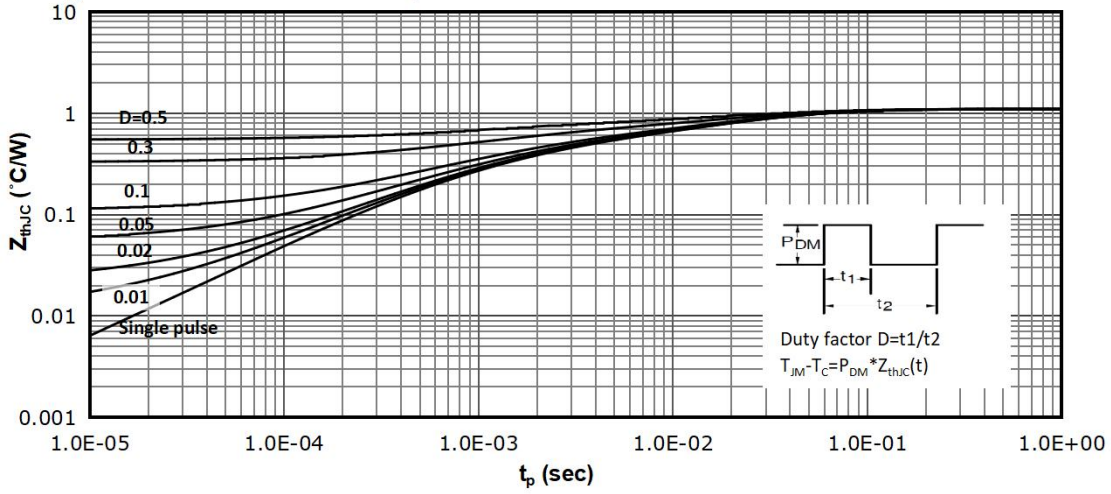


Fig 18: Rg(Ω) vs. Switching Times(us)

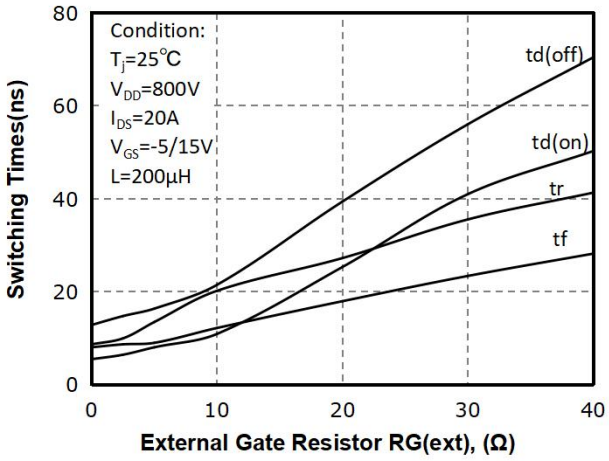


Fig 19: Rg(Ω) vs. Switching Loss(uJ)

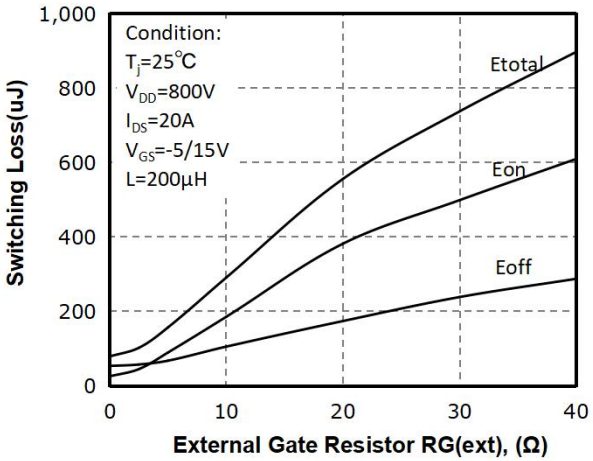


Fig 20: Temperature(°C) vs. Switching Loss(uJ)

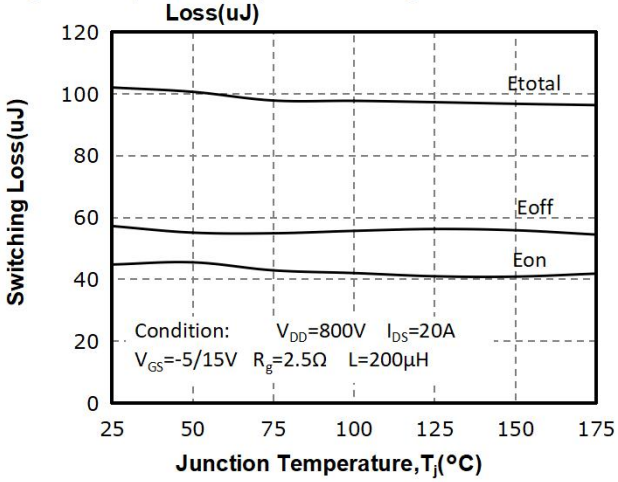
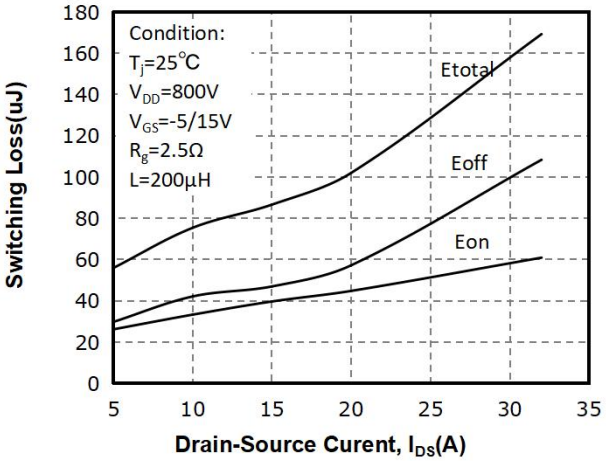
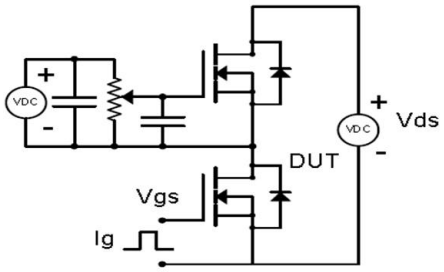


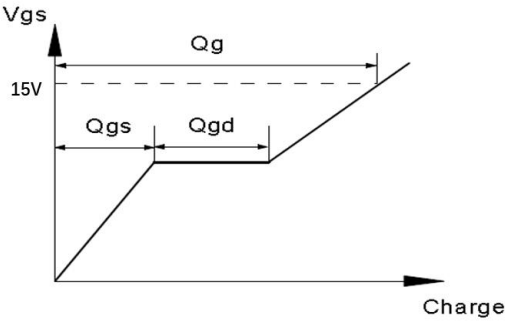
Fig 21: I_{DS}(A) vs. Switching Loss(uJ)



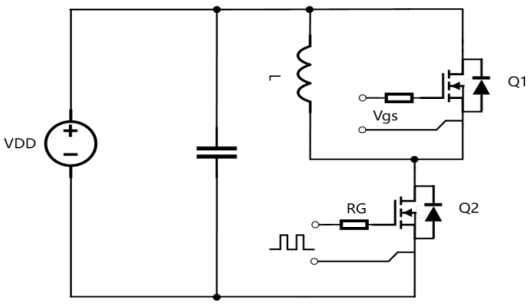
Test Circuit & Waveform

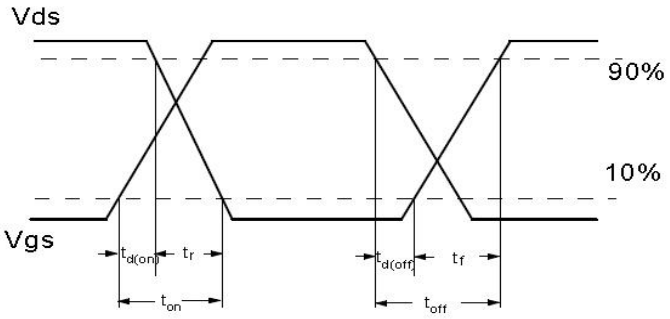
Gate Charge Test Circuit & Waveform



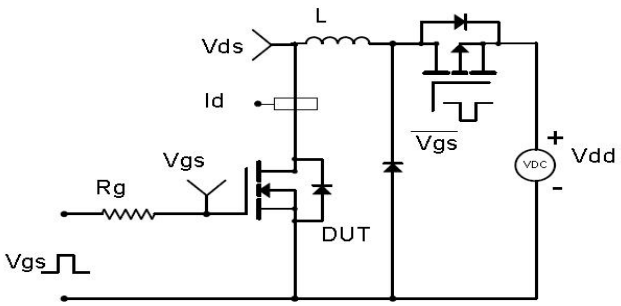


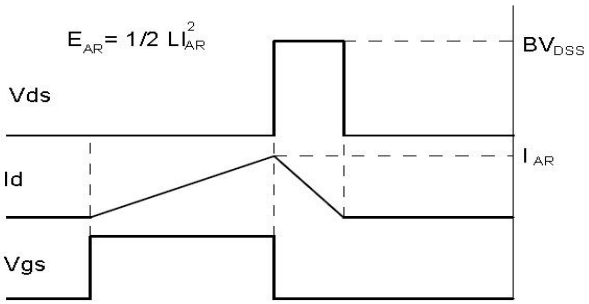
Resistive Switching Test Circuit & Waveforms



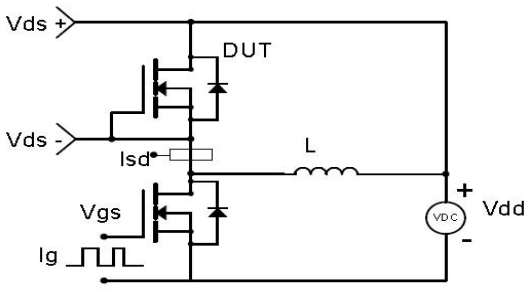


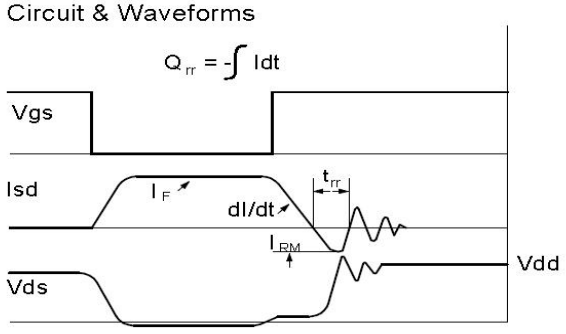
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



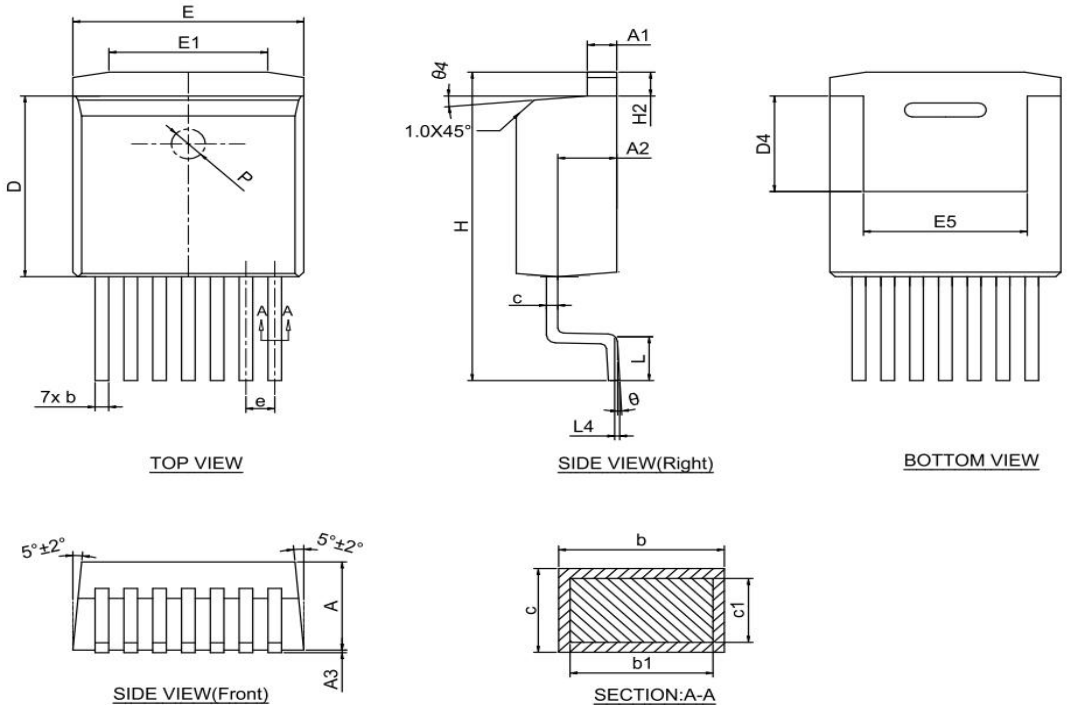


Diode Recovery Test Circuit & Waveforms





Package Outline: TO-263-7



Items	Values(mm)	
	MIN	MAX
A	4.2	4.66
A1	1.15	1.45
A2	2.35	2.85
A3	0	0.3
b	0.5	0.78
b1	0.45	0.75
c	0.49	0.64
c1	0.4	0.6
D	8.83	9.33
D4	4.6	5
e	1.27 BSC.	
E	9.08	10.38
E1	6.4	7.6
E5	6.72	7.72
H	14.9	16.1
H2	0.9	1.45
L	1.8	2.6
L4	0.25 BCS.	
P	1.4	1.6
θ	0°	7°

Revision History

Revison	Date	Major changes
1.0	2026/4/8	Release of formal version

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• CRM reserves the right to change any product or information in this Specification at any time without prior notice.

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• Any and all semicondutor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.